3D Packaging and Integration Japan TC Chapter

Japan Standards Winter 2021 Meetings

Monday, May 28, 2021,

Web conference

14:00-17:00

AGENDA

1 Welcome / Call to Order

1.1 Introductions

1.2 Meeting Reminders (Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting of 3D Packaging & Integration Japan TC Chapter

3 Liaison Report

3.1 NA TC Chapter

3.2 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

5.1 Cycle 3-2021 submitted by the Japan TC Chapter

5.1.1.1 6703 - Revision of SEMI G63-95 (Reapproved 0811) TEST METHOD FOR MEASUREMENT OF DIE SHEAR STRENGTH

6 Task Force & Study Group Reports

6.1 GCS

6.2 3D Packaging & Integration 5 Year Review Task Force

6.3 3DS IC Bonded Layer Inspection Metrology Task Force

6.4 450 mm Assembly & Test Die Preparation (ATDP) Task Force

6.5 Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force

6.6 Panel Level Packaging (PLP) Glass Carrier Task Force

6.7 Thin Chip Handling Task Force

6.8 3D Packaging & Integration Steering Group

7 Old Business

7.1 Project Period Review

7.2 5 Year Review Check

8 New Business

8.1 SNARF Submission

8.2 Review of G13,G70,and G75

9 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10 Next Meeting and Adjournment